

ABSTRACT

METHOD AND APPARATUS FOR MOLDING

A SEMICONDUCTOR DEVICE

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A method and apparatus is provided for molding a semiconductor device in a mold including two mold halves. One mold half includes a compressible sealing mechanism constructed and configured to exert a sealing pressure
10 between a surface of the mold half and a surface of a semiconductor device located in the mold. A compliant tape is positionable onto the mold half comprising the sealing mechanism between the semiconductor device and the sealing mechanism for molding of the semiconductor device.

15 (FIG. 1)